

This listing of claims will replace all prior versions of claims in the application.

Claims 1-36 (cancelled).

Claim 37 (previously presented): A photoresist composition that comprises:

- (a) a photoacid generator compound; and
- (b) a polymer that comprises a hydroxyadamantyl moiety, a polymerized norbornene group and at least two distinct repeat units that each has a photoacid-labile group.

Claim 38 (previously presented): The photoresist composition of claim 37 wherein the polymer comprises a lactone group.

Claim 39 (previously presented): The photoresist composition of claim 37 wherein the polymer comprises polymerized acrylate groups that comprise one or more photoacid-labile moieties.

Claim 40 (previously presented): The photoresist composition of claim 37 wherein the polymer comprises one or more nitrile moieties.

Claim 41 (cancelled).

Claim 42 (previously presented): The photoresist composition of claim 37 wherein the polymer is a terpolymer.

Claim 43 (previously presented): The photoresist composition of claim 37 wherein the polymer is a tetrapolymer.

Claim 44 (previously presented): The photoresist of claim 37 wherein the polymer is

substantially free of aromatic groups.

Claim 45 (previously presented): The photoresist composition of claim 37 wherein the polymer is completely free of aromatic groups.

Claim 46 (previously presented): A microelectronic wafer substrate having coated thereon a layer of the photoresist composition of claim 37.

Claim 47 (previously presented): A photoresist composition that comprises:

- (a) a photoacid generator compound; and
- (b) a polymer that comprises a hydroxyadamantyl moiety, a polymerized norbornene group and a lactone group.

Claim 48 (previously presented): The photoresist composition of claim 47 wherein the polymer is at least substantially free of aromatic groups.

Claim 49 (previously presented): The photoresist composition of claim 47 wherein the polymer comprises polymerized acrylate groups that comprise one or more photoacid-labile moieties.

Claim 50 (previously presented): The photoresist composition of claim 47 wherein the polymer comprises one or more nitrile moieties.